



Material Content Data Sheet



Sales Product Name	BSS84PW H6327			Issued		14. September 2018		
MA#	MA002497752							
Package	PG-SOT323-3-3			Weight*		5.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.03		289	
	noble metal	gold	7440-57-5	0.007	0.11		1119	
	inorganic material	silicon	7440-21-3	0.076	1.27	1.41	12686	14094
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		440	
	non noble metal	chromium	7440-47-3	0.008	0.13		1321	
	non noble metal	copper	7440-50-8	2.617	43.84	44.02	438414	440263
wire	non noble metal	copper	7440-50-8	0.005	0.09	0.09	852	852
encapsulation	organic material	carbon black	1333-86-4	0.031	0.52		5209	
	plastics	epoxy resin	-	0.668	11.20		111990	
	inorganic material	silicondioxide	60676-86-0	2.410	40.37	52.09	403684	520883
leadfinish	non noble metal	tin	7440-31-5	0.133	2.22	2.22	22231	22231
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1677	1677
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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